

ABSTRACT

A double-sided or multilayer wiring board having high-density wiring is obtained by embedding a spherical semiconductor element in an electrically insulating substrate which composes the wiring board, and a thin electronic device can be provided using such a wiring board. Furthermore, a flexible double-sided or multilayer wiring board which is capable of being housed in a limited space while keeping a desired form can be provided by embedding the spherical semiconductor element, and a thin electronic device can be provided using a variety of such wiring boards by imparting different types of flexibility to desired parts of such a wiring board as required.